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**LOCTITE C 400**

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**PRODUCT DESCRIPTION**

LOCTITE C 400 provides the following product characteristics:

<b>Technology</b>	Cored solder wire
Product Benefits	<ul style="list-style-type: none"><li>• Halide free</li><li>• No clean</li><li>• Clear residue</li><li>• Good wetting</li><li>• Fast soldering</li><li>• Heat stable</li><li>• Mild odor</li><li>• Pb-free and SnPb alloys available</li></ul>
IPC/J-STD-004 Classification	ROL0
<b>Application</b>	Soldering - Cored wire
Surface Finishes	Copper, Brass and Nickel

LOCTITE C 400 cored solder wire has been specially formulated to complement no clean wave and reflow soldering processes. LOCTITE C 400 wires provide fast soldering on copper, brass, and solder coated materials.

**TYPICAL PROPERTIES****Solder Cored Wire**

Alloys - Tin/lead	<ul style="list-style-type: none"><li>• SN63</li><li>• SN60</li><li>• Sn62</li></ul>
Alloys - Lead Free	<ul style="list-style-type: none"><li>• 97SC (SAC305)</li><li>• 96SC (SAC387)</li><li>• SAC0307</li><li>• 99C (SnCu)</li><li>• 95A (SnSb)</li><li>• 96S (SnAg)</li></ul>
Acid Value	205 to 220 mg KOH/g
Halide content	Zero
Flux Content (%)	2.2

**ALLOYS:**

The alloys used in LOCTITE C 400 cored solder wires conform to the purity requirements of the common national and international standards.

**FLUX:**

LOCTITE C 400 solid flux is based on modified rosin and carefully selected activators. In practice they exhibit a mild rosin odor and leave a small quantity of clear residue.

**DIRECTIONS FOR USE**

Soldering with LOCTITE C 400 does not require any special methods or deviation from standard hand soldering practices.

**Soldering Iron:**

- Good results can be obtained using a range of tip temperatures. However, the optimum tip temperature and heat capacity required for a hand-soldering process is a function of both soldering iron design and the nature of the task.
- Care should be exercised to avoid unnecessarily high tip temperatures for extensive periods of time.
- A high tip temperature may increase any tendency to flux spitting and it may produce some residue darkening.
- The tip of the soldering iron should be properly tinned. Severely contaminated soldering iron tips should be cleaned with Multicore<sup>®</sup> Tip Tinner/Cleaner.
- Wipe the tip on a clean, damp sponge before re-tinning with LOCTITE C 400 wire.

**Soldering Process:**

1. Apply the soldering iron tip to the work surface. The iron tip should contact both the base material and the lead at the same time to heat both surfaces properly. It should take no more than a fraction of a second to heat both surfaces adequately.
2. Apply LOCTITE C 400 flux cored wire to a part of the joint surface away from the soldering iron and allow to form a joint fillet. This will be virtually instantaneous. Do not apply excessive solder to the joint as this will not improve joint integrity and it will leave excess flux residues on the surface.
3. Remove solder from the work piece and then remove the iron tip.
4. The total process will be very rapid, depending upon thermal mass, tip temperature, tip configuration and the solderability of the surfaces to be joined.
5. The resin and flux systems are designed to leave relatively low residues and to minimize residual activity. This is achieved by ensuring some decomposition and volatilization takes place during the soldering process

**Cleaning:**

LOCTITE C 400 flux cored solder wire has been formulated to leave amber flux residues and resist spitting and fuming. In most industrial and consumer electronics applications, cleaning will not be required. The product may, therefore, be used to complement a no-clean wave soldering or reflow process or to allow repairs to cleaned boards without the need for a second cleaning process. In high-reliability applications, the residues should be removed.

Should cleaning be required, this is best achieved using SC-01<sup>™</sup> cleaner.

**RELIABILITY PROPERTIES**

J-STD-004	Solder spread mm <sup>2</sup>	210
	Corrosion Test	Pass
Surface Insulation Resistance (SIR) (without cleaning)	IPC-SF-818 Class 3	Pass
	Bellcore TR-NWT-000078	Pass
Electromigration (without cleaning)	Bellcore TR-TSY-000078	Pass
Classification	EN29454-1	Pass
	IPC-SF-818	Pass

**PACKAGING**

LOCTITE C 400 is available in various diameters, flux percentages, and reel sizes.

**DATA RANGES**

The data contained herein may be reported as a typical value and/or a range. Values are based on actual test data and are verified on a periodic basis.

**GENERAL INFORMATION**

**For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).**

**Not for Product Specifications**

The technical information contained herein is intended for reference only. Please contact Henkel Corporation Technical Service for assistance and recommendations on specifications for this product.

**Conversions**

(°C x 1.8) + 32 = °F

kV/mm x 25.4 = V/mil

mm / 25.4 = inches

µm / 25.4 = mil

N x 0.225 = lb

N/mm x 5.71 = lb/in

N/mm<sup>2</sup> x 145 = psi

MPa x 145 = psi

N·m x 8.851 = lb·in

N·m x 0.738 = lb·ft

N·mm x 0.142 = oz·in

mPa·s = cP

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Reference 0.3